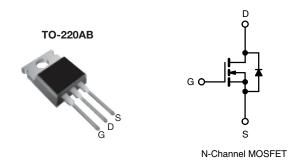


COMPLIANT

Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	60			
R _{DS(on)} (Ω)	V _{GS} = 10 V 0.018			
Q _g (Max.) (nC)	110			
Q _{gs} (nC)	29			
Q _{gd} (nC)	36			
Configuration	Single			



FEATURES

- Advanced Process Technology
- Ultra Low On-Resistance
- Dynamic dV/dt Rating
- 175 °C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Drop in Replacement of the SiHFZ48 for Linear/Audio Applications
- Compliant to RoHS Directive 2002/95/EC

DESCRIPTION

Advanced Power MOSFETs from Vishay utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that Power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION		
Package	TO-220AB	
Lead (Pb)-free	IRFZ48RPbF	
Lead (Fb)-life	SiHFZ48R-E3	
SnPb	IRFZ48R	
SIFU	SiHFZ48R	

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	60	V	
Gate-Source Voltage			V_{GS}	± 20	V	
Continuous Drain Current	V _{GS} at 10 V	T _C = 25 °C T _C = 100 °C	I_	50	А	
Continuous Drain Current		T _C = 100 °C	ID	50		
Pulsed Drain Current ^a			I _{DM}	290	1	
Linear Derating Factor				1.3	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	100	mJ	
Repetitive Avalanche Current ^a			I _{AR}	50	Α	
Repetitive Avalanche Energy ^a			E _{AR}	19	mJ	
Maximum Power Dissipation	Power Dissipation T _C = 25 °C		P_{D}	190	W	
Peak Diode Recovery dV/dtc			dV/dt	4.5	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 175	°C	
Soldering Recommendations (Peak Temperature) for 10 s			300 ^d			
Mounting Toyour	6-32 or M3 screw			10	lbf ⋅ in	
Mounting Torque				1.1	N · m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b. $V_{DD}=25$ V, starting $T_J=25$ °C, L=22 µH, $R_g=25$ Ω $I_{AS}=72$ A (see fig. 12). c. $I_{SD}\leq72$ A, $dV/dt\leq200$ A/µs, $V_{DD}\leq V_{DS}$, $T_J\leq175$ °C. d. 1.6 mm from case.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	62		
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.50	-	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	0.8		

PARAMETER	SYMBOL	TEST (CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static				•	•	•	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0$	V, I _D = 250 μA	60	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	0.060	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_0$	_{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}	Vo	_{SS} = ± 20	-	-	± 100	nA
Zoro Coto Voltago Drain Current	1	V _{DS} = 6	0 V, V _{GS} = 0 V	-	-	25	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 48 V, V _{GS} = 0 V, T _J = 150 °C		-	250	μA	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 43 A ^b	-	-	0.018	Ω
Forward Transconductance	9 _{fs}	V _{DS} = 2	5 V, I _D = 43 A ^b	27	-	-	S
Dynamic							
Input Capacitance	C _{iss}	V	_{GS} = 0 V,	-	2400	-	
Output Capacitance	C _{oss}	$V_{DS} = 25 \text{ V},$		-	1300	-	рF
Reverse Transfer Capacitance	C _{rss}	f = 1.0 ľ	MHz, see fig. 5	-	190	-	
Total Gate Charge	Qg			-	-	110	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 72 \text{ A}, V_{DS} = 48 \text{ V},$ see fig. 6 and 13 ^b	-	-	29	nC
Gate-Drain Charge	Q_{gd}]	ooo ng. o ana ro	-	-	36	
Turn-On Delay Time	t _{d(on)}			-	8.1	-	
Rise Time	t _r	V _{DD} = 3	ΛV I _D = 72 Δ	-	250	-	
Turn-Off Delay Time	t _{d(off)}	$R_g = 9.1 \Omega$, $R_D = 0.34 \Omega$, see fig. 10^b		-	210	-	ns
Fall Time	t _f			-	1		
Internal Drain Inductance	L _D	6 mm (0.25") from		-	4.5	-	
Internal Source Inductance	L _S	package and cei die contact	nter of	-	7.5	-	- nH
Drain-Source Body Diode Characteristic	s					·	ı
Continuous Source-Drain Diode Current	I _S	MOSFET symbo showing the	I	-	-	50	_
Pulsed Diode Forward Current ^a	I _{SM}	integral reverse p - n junction diode		-	-	290	- A
Body Diode Voltage	V_{SD}	T _J = 25 °C, I _S	$_{S} = 72 \text{ A}, V_{GS} = 0 \text{ V}^{b}$	-	-	2.0	V
Body Diode Reverse Recovery Time	t _{rr}	T 25 °C 1	70 A dl/dt = 100 A/h	-	120	180	ns
Body Diode Reverse Recovery Charge	Q _{rr}	IJ = 25 ⁻ U, I _F =	72 A, dl/dt = 100 A/µs ^b	-	0.50	0.80	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S		v Ls and	LD)		

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

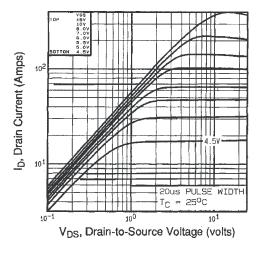


Fig. 1 - Typical Output Characteristics

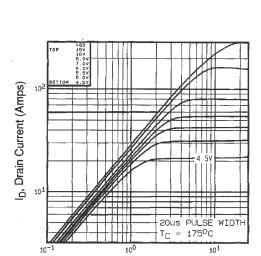


Fig. 2 - Typical Output Characteristics

V_{DS}, Drain-to-Source Voltage (volts)

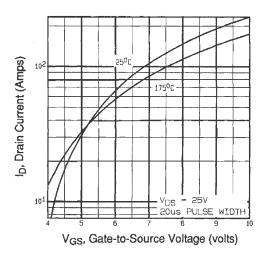


Fig. 3 - Typical Transfer Characteristics

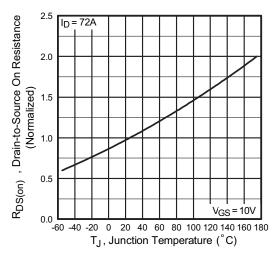


Fig. 4 - Normalized On-Resistance vs. Temperature



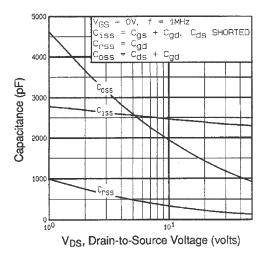


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

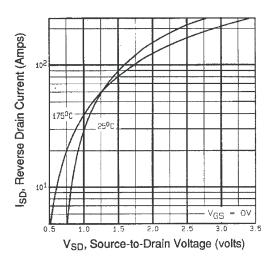


Fig. 7 - Typical Source-Drain Diode Forward Voltage

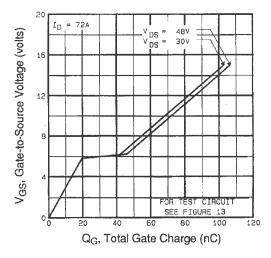


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

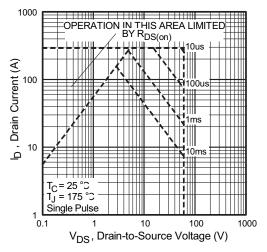


Fig. 8 - Maximum Safe Operating Area





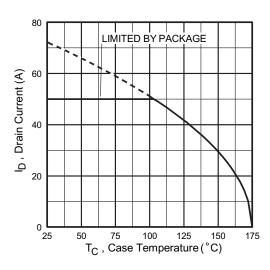


Fig. 9 - Maximum Drain Current vs. Case Temperature

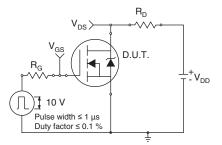


Fig. 10a - Switching Time Test Circuit

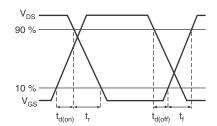


Fig. 10b - Switching Time Waveforms

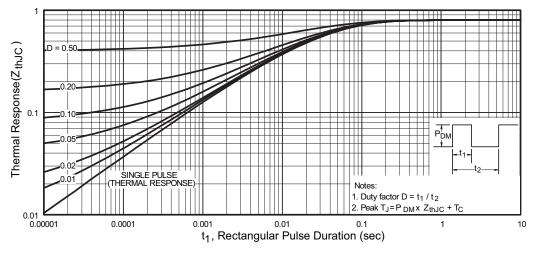


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



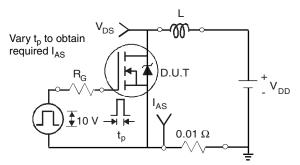


Fig. 12a - Unclamped Inductive Test Circuit

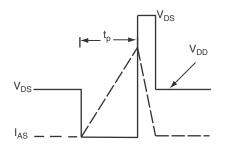


Fig. 12b - Unclamped Inductive Waveforms

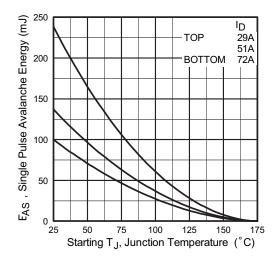


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

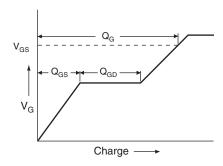


Fig. 13a - Basic Gate Charge Waveform

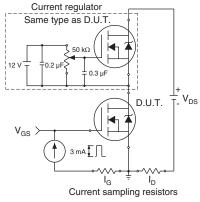
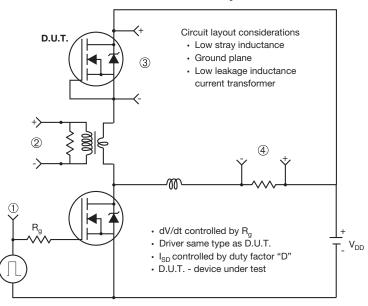


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



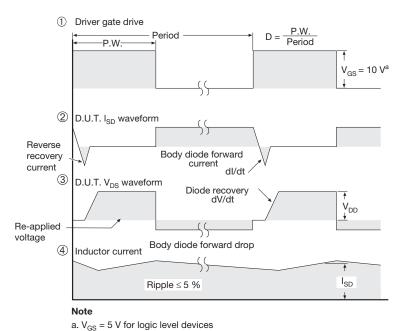


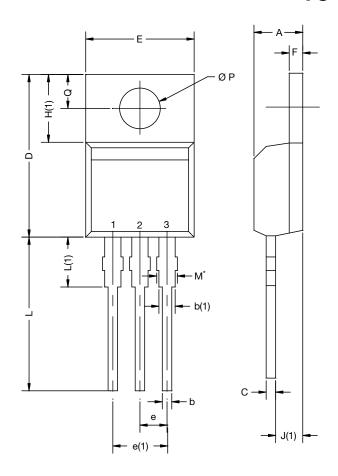
Fig. 14 - For N-Channel

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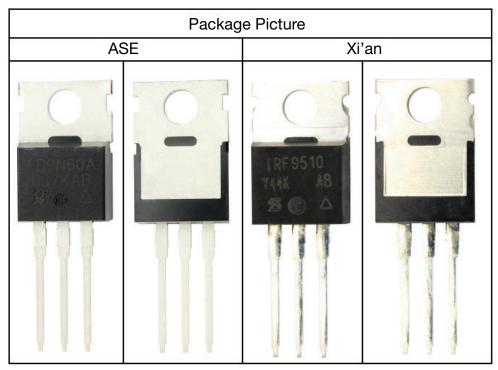
TO-220-1



DIM.	MILLIN	METERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	

Note

 \bullet $M^{\star}=0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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